

## F850

## GaAs HBT Gain Block MMIC Amplifier 50MHz-3GHz

March 2015 Rev 1

### Features

- © 50MHz 3 GHz
- ◎ +20 dBm P-1dB at 1 GHz
- ◎+36dBm OIP3 at 1 GHz
- © 20dB Gain at 1GHz
- © 2.8 dB Noise Figure at 2GHz
- SOT 89 Package Style

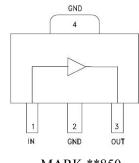
#### Description

The *F850* is a general-purpose buffer amplifier that offers high dynamic range in a low-cost surface-mount package. at 50MHz, the *F850* typically provides 21 dB of gain, +38 dBm Output IP3, and +21dBm P1dB. The *F850* consists of Darlington pair amplifiers using the high reliability InGaP/GaAs HBT process technology and only requires DC-blocking capacitors, a bias resistor, and an inductive RF choke for operation.

## Applications

- O Mobile Infrastructure
- O CATV / FTTX
- O W-LAN / ISM
- © RFID
- © WiMAX/WiBro

#### **Functional Diagram**



MARK \*\*850

## Electrical Characteristics (Vcc= 5V, TA = +25 $^\circ\!\!\!\!\mathrm{C}\,,~75\Omega$ )

Parameter		Min.	Тур.	Max.	Units	
Gain	50MHz~500MHz	20.5	21.0			
	50MHz~3GHz	18.0	18.5		dB	
Input return Loss	50MHz ~3 GHz	10	12		dB	
Output return Loss	50MHz ~3 GHz	10	12		dB	
Output Power for 1 dB Compression (P1dB)	50MHz~500MHz	20.5	21.0		dBm	
	500MHz~3GHz	19.6	20.0			
Output Third Order Intercept (IP3)	50MHz~500MHz	37.2	38			
	500MHz~3GHz	36.2	37		dBm	
Noise Figure	50MHz~3GHz		2.8	3.4	dB	
Device Voltage			5.0	5.5	v	
Supply Current		72	82		mA	



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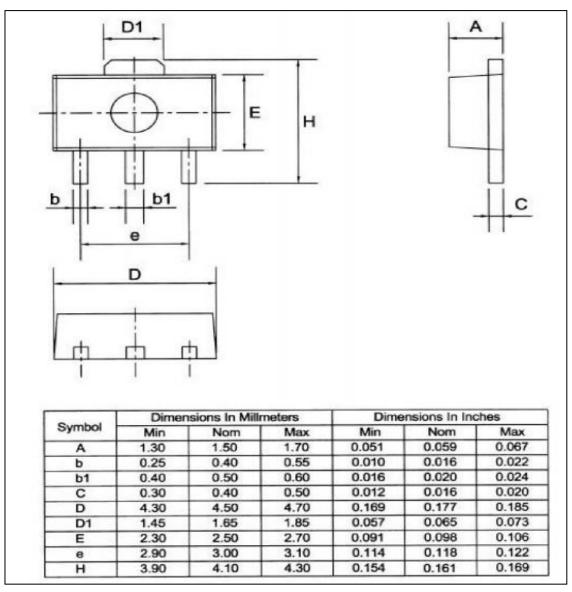
#### **Absolute Maximum Ratings**

Device Current	110mA
Storage Temperature	-65 to +150°C
<b>Operating Temperature</b>	-55 to +125°C
ESD Sensitivity (HBM)	Class 1A

ELECTROSTATIC SENSITIVE DEVICE

ESD Rating: Class 1A Value: Passes between 1500 and 2000V Test: Human Body Model (HBM) Standard: JEDEC Standard JESD22-A114

#### **Outline Drawing**



Specifications and data presented may change without notice



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#### **Pin Descriptions**

Pin number	Function	Description	
1	RF <sub>IN</sub>	This pin is DC coupled;An off chip DC blocking capacitor is required.	
2, 4	GND	These pins and package bottom must be connected to RF/DC ground.	
3	RFout	RF output and DC Bias for the output stage.	

## DCO-C2 1uF C3 C4 1200pF 10nF LI 680nH C5 C1RF in RF out F850 1000pF 1000pF 4 DC 5V F850 IN OUT C C 5

#### **Application Circuit**